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# CSI™ Razor

## Preliminary Product Brief

### Overview

The CSI™ Razor is the smart choice for reducing the cost and size of QFN packages while enhancing performance. It enables improvements achieved through the printing of packaging components on a stainless steel carrier which is removed after assembly and testing.

For a common package size of 88 leads, the Razor provides up to a 23% footprint reduction, and improved thermal and electrical performance over a standard QFN leadframe.

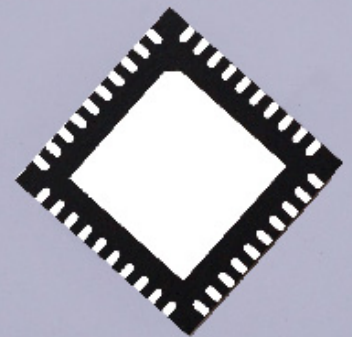
The below data is for reference only. For detailed analysis on specific packages, contact EoPlex at info@eoplex.com.

### Thermal Performance

Lead Count	Package Size (mm)	DAP Size (mm)	θJA (°C/W)		
			0 m/s	1 m/s	2 m/s
4	1 x 1	0.60	87.60	85.61	83.60
16	3 x 3	2.00	51.40	49.38	47.37
40	6 x 6	4.30	22.60	20.57	18.56

### Electrical Performance

Lead Count	Package Size (mm)	DAP Size (mm)	Ls(nH)	Lm(nH)	C(pf)	Cm(pf)
4	1 x 1	0.60	0.41	0.20	0.10	0.02
16	3 x 3	2.00	0.51	0.24	0.11	0.03
40	6 x 6	4.30	1.10	0.42	0.18	0.04



### Highlights

- Printed Components
- I/O Range, 2 to 88 Lead
- Multi-Row I/O
- Thin package, 0.25 mm
- Custom Design Flexibility
- Green Process

### Specifications

- Wire Bond: Gold or Copper
- Lead Finish: Sintered Silver
- Bond Pad Pitch: > 0.2mm

### Application Areas

- Low Lead Applications
- Mobile Computing
- IOT Devices
- Automotive
- Camera Systems
- Analog RF Devices